

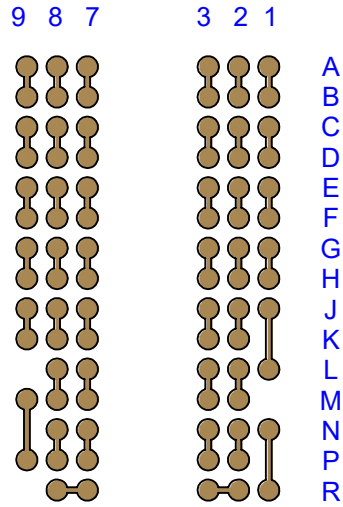
Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.45mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.36mm (14 mil).
- 5) PAD Cu DIAMETER: 0.56mm (22 mil).
- 6) SUBSTRATE MATERIAL: FR4 (ALTERNATIVE: BT).
- 7) DUMMY DIE: 0.25mm (10 mil) THICK.
- 8) DAISY CHAIN PATTERN (SEE PAGE 2).
- 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

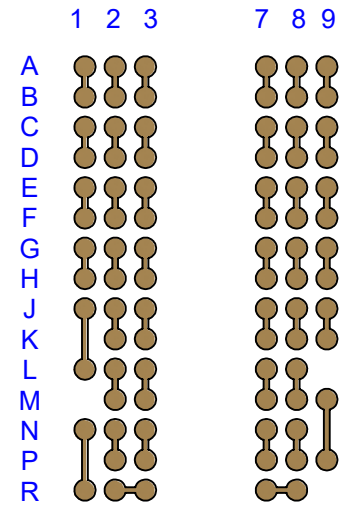
PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
BGA84T.8C-DC656D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
BGA84T.8-DC656D	Sn63/Pb37	NO	NO	YES

APPROVALS		DATE	TopLine ®			
DRAWN	T. Au	6/23/2021	TITLE BGA84T.8C-DC656D DAISY CHAIN DUMMY			
ENG	M. Hart	6/23/2021				
MFG			SCALE	SIZE	DRAWING NO.	REV
QA			7.5:1	A	586552	A
CUST			DO NOT SCALE DRAWING			SHEET 1 OF 3

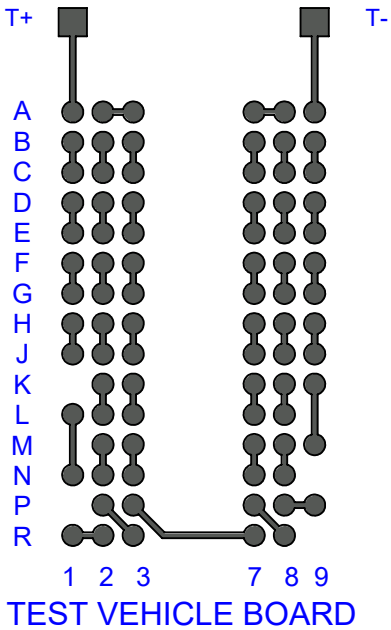
BALL VIEW



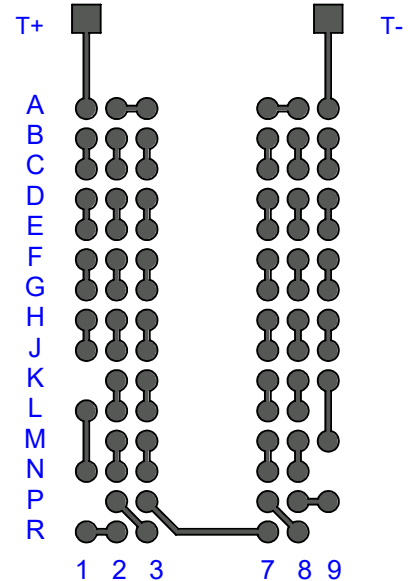
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)

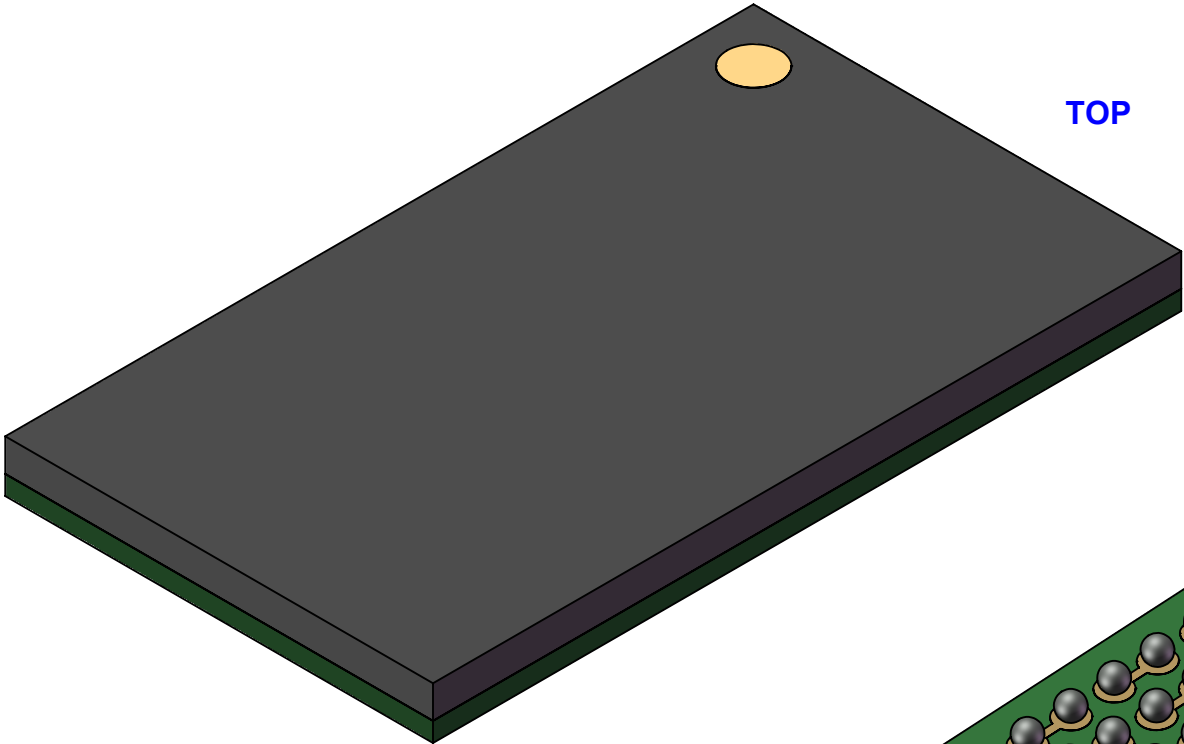


- Notes:
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
 - 2) PCB Cu BALL PAD DIAMETER 0.56mm (22mil).
 - 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm (6mil).
 - 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.36mm (14mil).

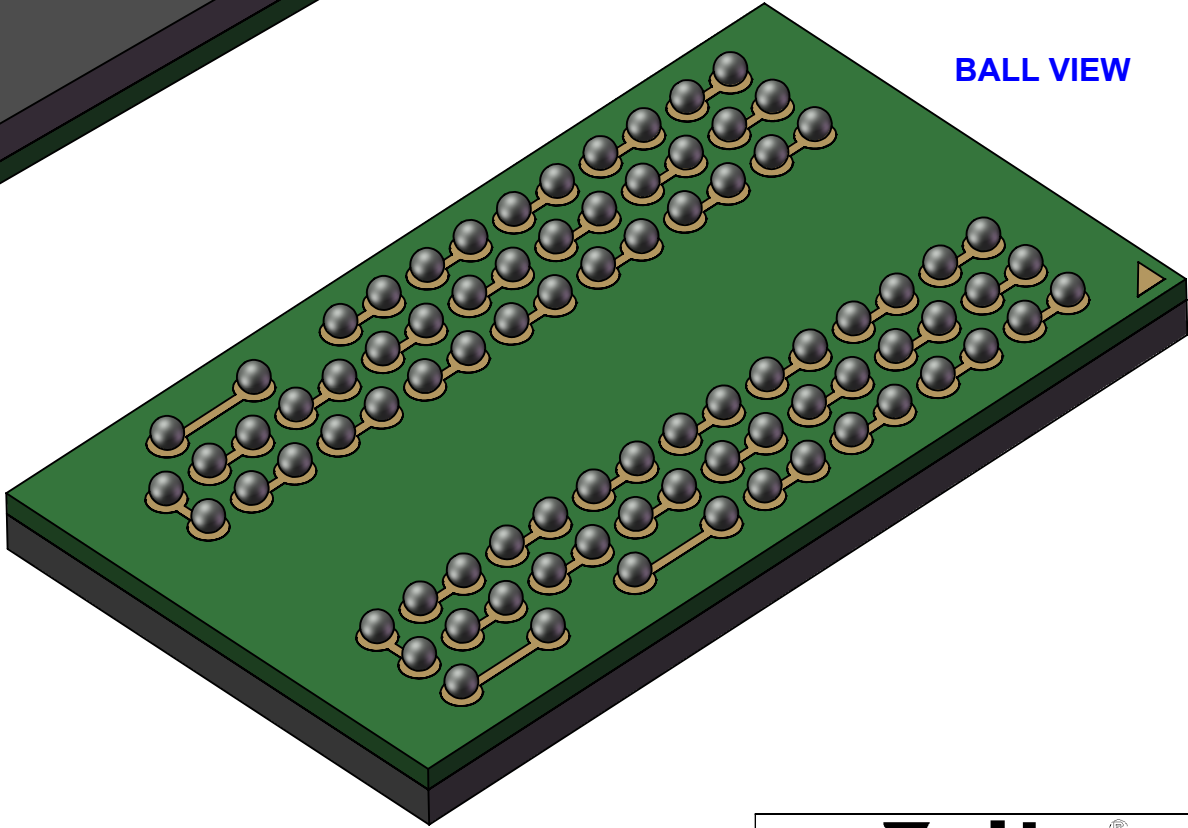
TopLine ®			
TITLE		BGA84T.8C-DC656D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
5:1	A	586552	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

MODEL VIEWS

TOP



BALL VIEW



TopLine [®]			
TITLE BGA84T.8C-DC656D DAISY CHAIN DUMMY			
SCALE	SIZE	DRAWING NO.	REV
10:1	A	586552	A
DO NOT SCALE DRAWING			SHEET 3 OF 3